

FMI12N50ES

FUJI POWER MOSFET

Super FAP-E^{3S} series

N-CHANNEL SILICON POWER MOSFET

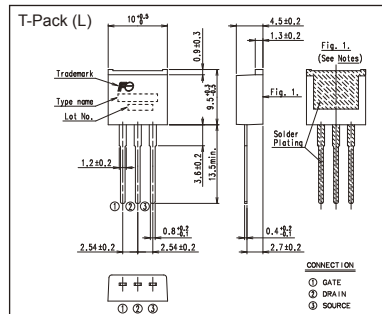
Features

- Maintains both low power loss and low noise
- Lower $R_{DS(on)}$ characteristic
- More controllable switching dv/dt by gate resistance
- Smaller V_{GS} ringing waveform during switching
- Narrow band of the gate threshold voltage ($3.7 \pm 0.5V$)
- High avalanche durability

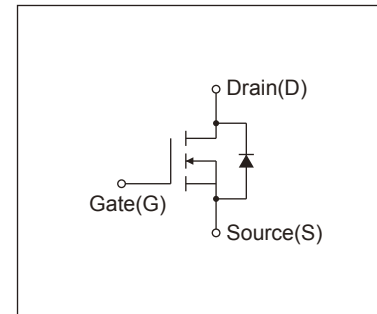
Applications

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

Outline Drawings [mm]



Equivalent circuit schematic



Maximum Ratings and Characteristics

Absolute Maximum Ratings at $T_c = 25^\circ C$ (unless otherwise specified)

| Description | Symbol | Characteristics | Unit | Remarks |
|---|-----------|-----------------|-------------|--------------------|
| Drain-Source Voltage | V_{DS} | 500 | V | |
| | V_{DSX} | 500 | V | $V_{GS} = -30V$ |
| Continuous Drain Current | I_D | ± 12 | A | |
| Pulsed Drain Current | I_{DP} | ± 48 | A | |
| Gate-Source Voltage | V_{GS} | ± 30 | V | |
| Repetitive and Non-Repetitive Maximum Avalanche Current | I_{AR} | 12 | A | Note*1 |
| Non-Repetitive Maximum Avalanche Energy | E_{AS} | 460.8 | mJ | Note*2 |
| Repetitive Maximum Avalanche Energy | E_{AR} | 18.0 | mJ | Note*3 |
| Peak Diode Recovery dV/dt | dV/dt | 6.3 | kV/ μs | Note*4 |
| Peak Diode Recovery $-di/dt$ | $-di/dt$ | 100 | A/ μs | Note*5 |
| Maximum Power Dissipation | P_D | 1.67 | W | $T_a = 25^\circ C$ |
| | | 180 | W | $T_c = 25^\circ C$ |
| Operating and Storage Temperature range | T_{ch} | 150 | $^\circ C$ | |
| | T_{slg} | -55 to + 150 | $^\circ C$ | |

Electrical Characteristics at $T_c = 25^\circ C$ (unless otherwise specified)

| Description | Symbol | Conditions | min. | typ. | max. | Unit |
|----------------------------------|--------------|---|------|-------|-------|----------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $I_D = 250 \mu A, V_{GS} = 0V$ | 500 | - | - | V |
| Gate Threshold Voltage | $V_{GS(th)}$ | $I_D = 250 \mu A, V_{DS} = V_{GS}$ | 3.2 | 3.7 | 4.2 | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 500V, V_{GS} = 0V$ | - | - | 25 | μA |
| | | $V_{DS} = 400V, V_{GS} = 0V$ | - | - | 250 | μA |
| Gate-Source Leakage Current | I_{GSS} | $V_{GS} = \pm 30V, V_{DS} = 0V$ | - | 10 | 100 | nA |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $I_D = 6A, V_{GS} = 10V$ | - | 0.427 | 0.50 | Ω |
| Forward Transconductance | g_{fs} | $I_D = 6A, V_{DS} = 25V$ | 4.5 | 9 | - | S |
| Input Capacitance | C_{iss} | $V_{DS} = 25V$ | - | 1400 | 2100 | pF |
| Output Capacitance | C_{oss} | $V_{GS} = 0V$ | - | 160 | 240 | pF |
| Reverse Transfer Capacitance | C_{rss} | $f = 1MHz$ | - | 11.5 | 17.5 | pF |
| Turn-On Time | $t_d(on)$ | $V_{cc} = 300V$ | - | 31 | 46.5 | ns |
| | t_r | $V_{GS} = 10V$ | - | 18 | 27 | ns |
| Turn-Off Time | $t_d(off)$ | $I_D = 6A$ | - | 83 | 124.5 | ns |
| | t_f | $R_G = 15\Omega$ | - | 16 | 27 | ns |
| Total Gate Charge | Q_G | $V_{cc} = 250V$ | - | 43 | 56 | nC |
| Gate-Source Charge | Q_{GS} | $I_D = 12A$ | - | 13 | 23 | nC |
| Gate-Drain Charge | Q_{GD} | $V_{GS} = 10V$ | - | 14 | 21 | nC |
| Gate-Drain Crossover Charge | Q_{SW} | | - | 6 | 10 | nC |
| Avalanche Capability | I_{AV} | $L = 2.44mH, T_{ch} = 25^\circ C$ | 12 | - | - | A |
| Diode Forward On-Voltage | V_{SD} | $I_F = 12A, V_{GS} = 0V, T_{ch} = 25^\circ C$ | - | 0.86 | 1.30 | V |
| Reverse Recovery Time | t_{rr} | $I_F = 12A, V_{GS} = 0V$ | - | 0.37 | - | μs |
| Reverse Recovery Charge | Q_{rr} | $-di/dt = 100A/\mu s, T_{ch} = 25^\circ C$ | - | 5.0 | - | μC |

Thermal Characteristics

| Description | Symbol | Test Conditions | min. | typ. | max. | Unit |
|--------------------|----------------|--------------------|------|------|-------|--------------|
| Thermal resistance | $R_{th(ch-c)}$ | Channel to Case | | | 0.690 | $^\circ C/W$ |
| | $R_{th(ch-a)}$ | Channel to Ambient | | | 75.0 | $^\circ C/W$ |

Note *1: $T_{ch} \leq 150^\circ C$.

Note *2: Stating $T_{ch} = 25^\circ C, I_{AS} = 5A, L = 33.8mH, V_{cc} = 50V, R_G = 50\Omega$.

E_{AS} limited by maximum channel temperature and avalanche current.

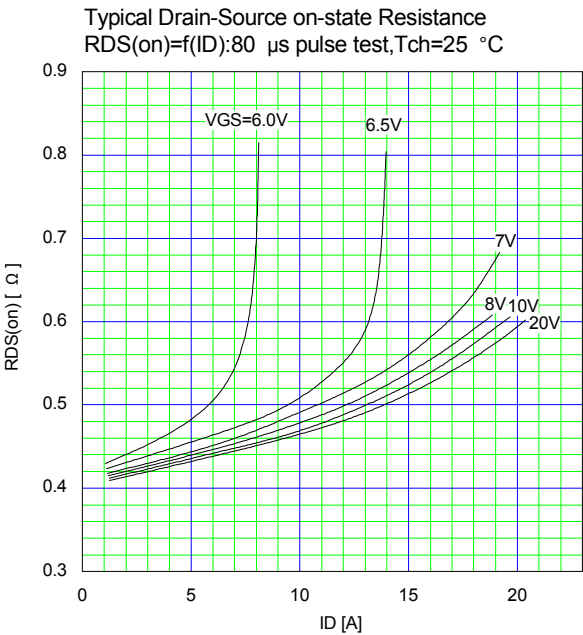
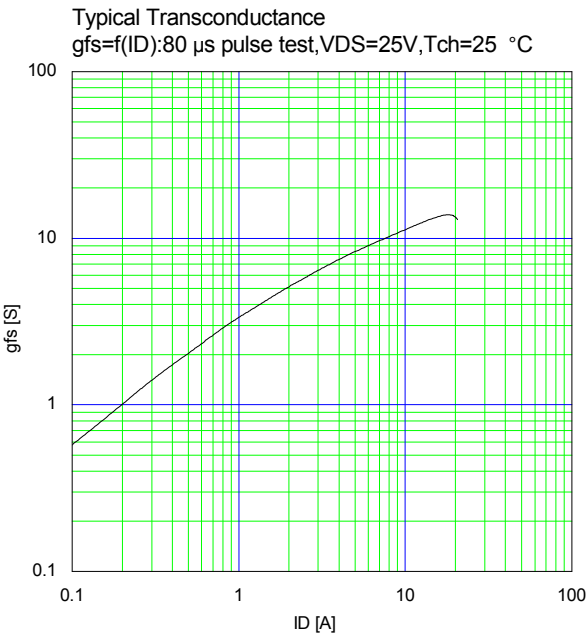
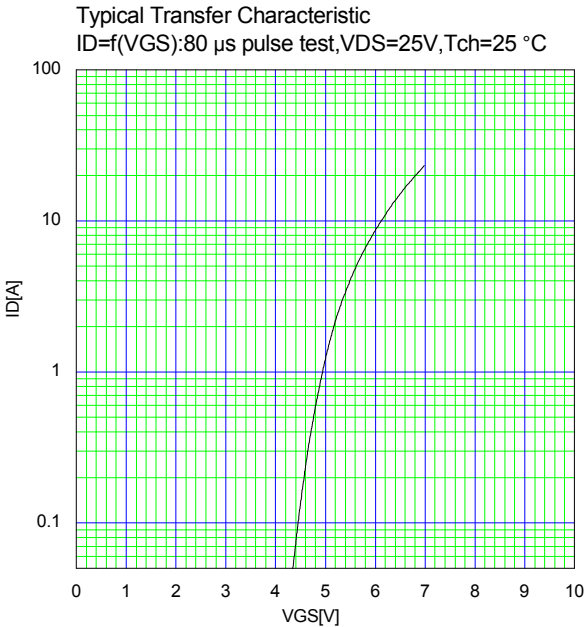
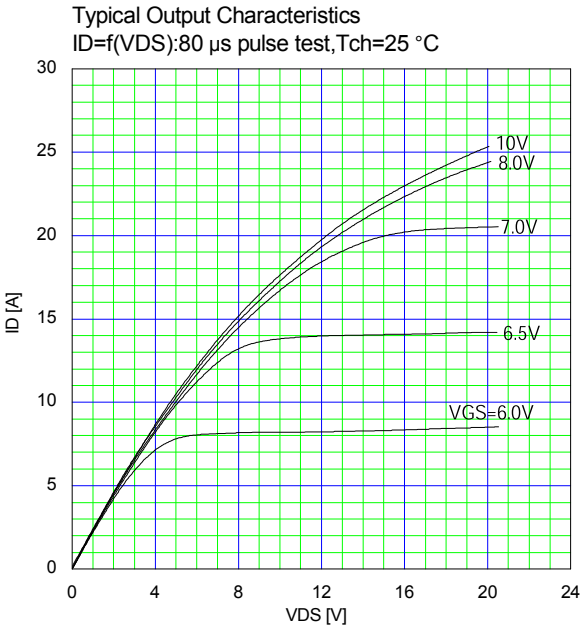
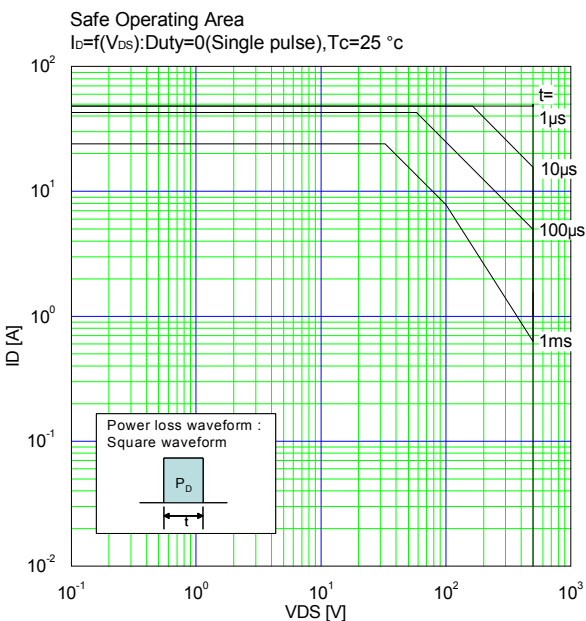
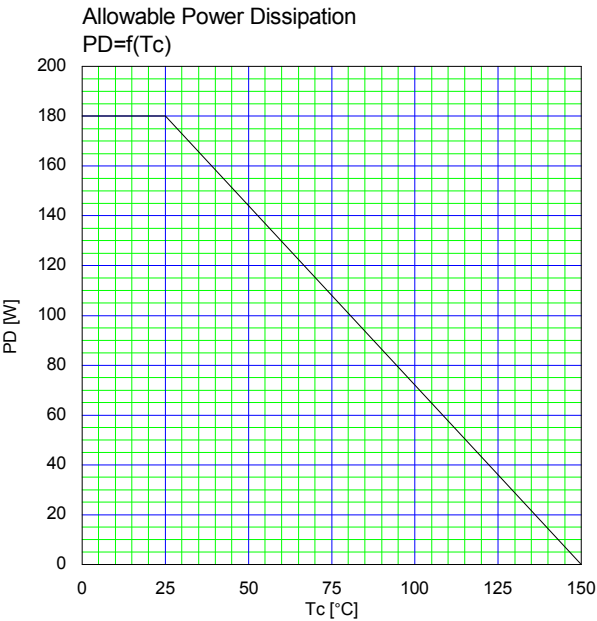
See to 'Avalanche Energy' graph.

Note *3: Repetitive rating: Pulse width limited by maximum channel temperature.

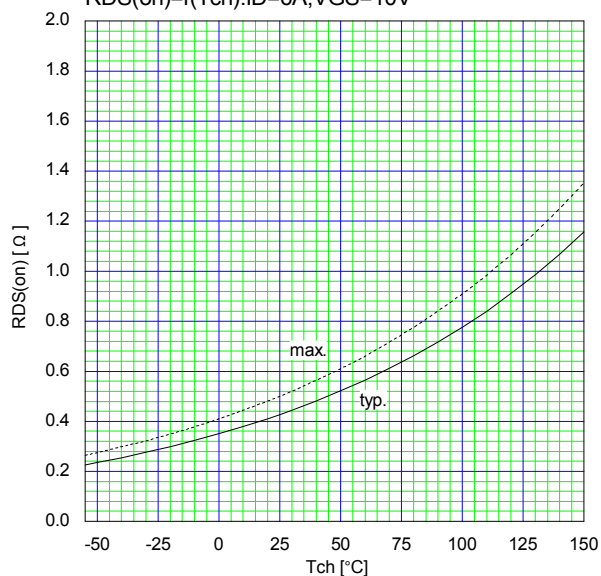
See to the 'Transient Thermal impedance' graph.

Note *4: $I_{FS} = I_D, -di/dt = 100A/\mu s, V_{cc} = BV_{DSS}, T_{ch} = 150^\circ C$.

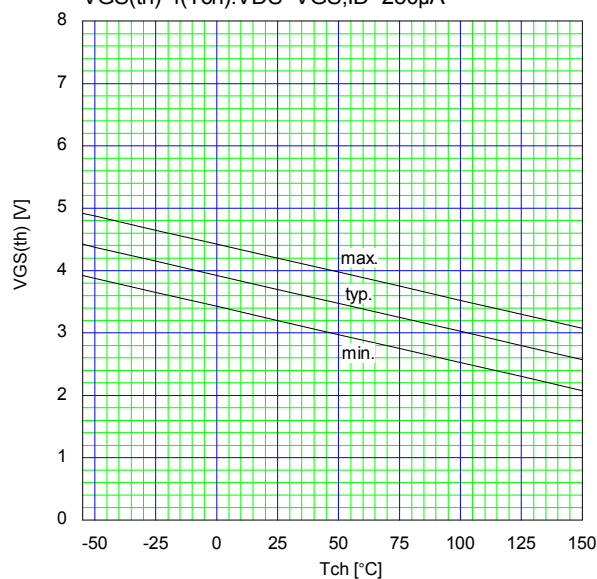
Note *5: $I_{FS} = I_D, dv/dt = 6.3kV/\mu s, V_{cc} = BV_{DSS}, T_{ch} = 150^\circ C$.



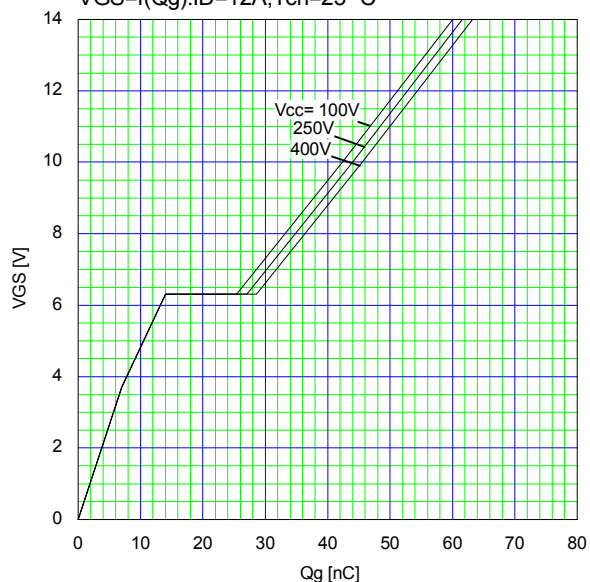
Drain-Source On-state Resistance
 $R_{DS(on)} = f(T_{ch}): I_D = 6A, V_{GS} = 10V$



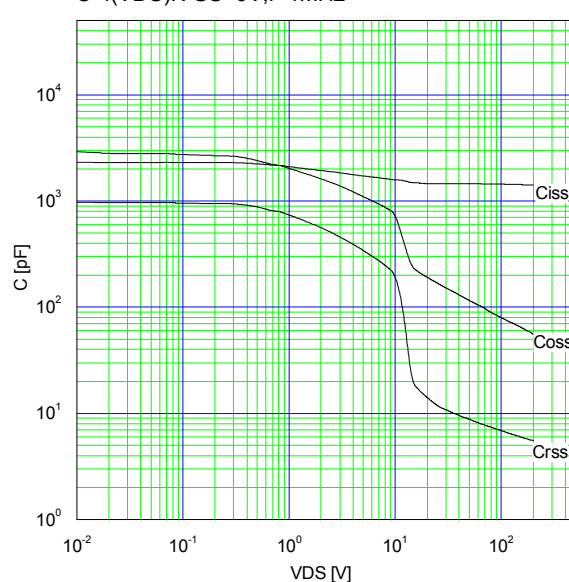
Gate Threshold Voltage vs. T_{ch}
 $V_{GS(th)} = f(T_{ch}): V_{DS} = V_{GS}, I_D = 250\mu A$



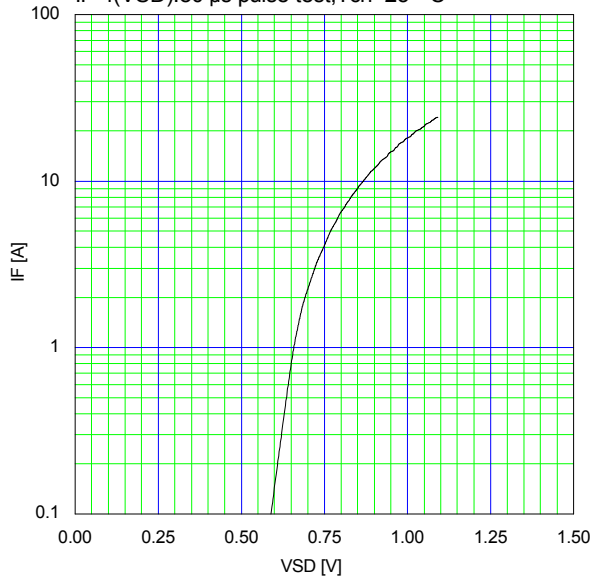
Typical Gate Charge Characteristics
 $V_{GS} = f(Q_g): I_D = 12A, T_{ch} = 25^\circ C$



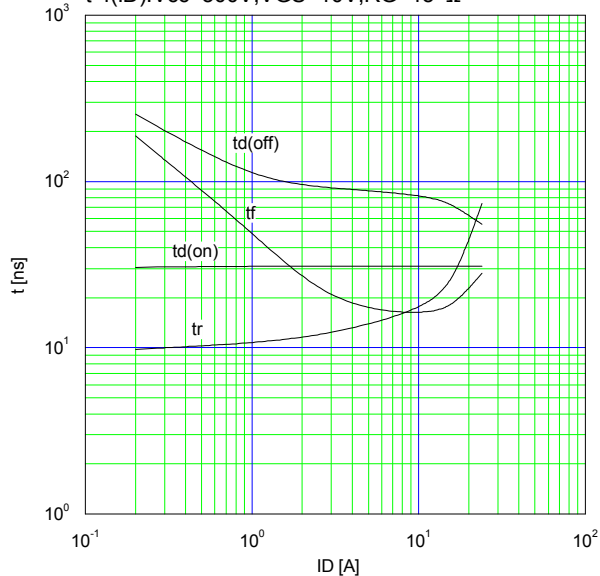
Typical Capacitance
 $C = f(V_{DS}): V_{GS} = 0V, f = 1MHz$

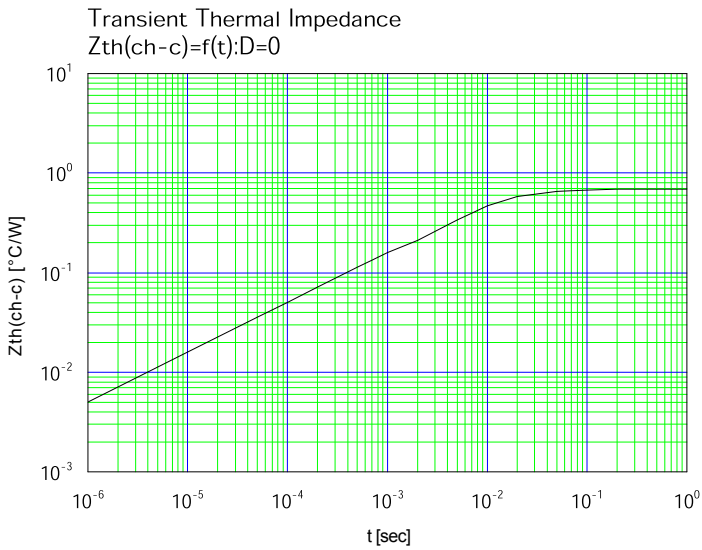
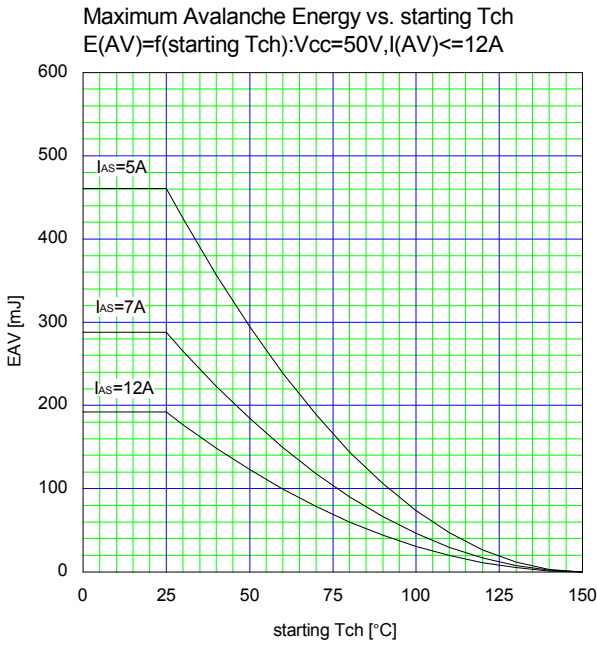


Typical Forward Characteristics of Reverse Diode
 $I_F = f(V_{SD}): 80\mu s$ pulse test, $T_{ch} = 25^\circ C$



Typical Switching Characteristics vs. I_D
 $t = f(I_D): V_{CC} = 300V, V_{GS} = 10V, R_G = 15\Omega$





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|-----------------|-------------------------|---|--------------------------|
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|--------------------------------|------------------------|-----------------------------|
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